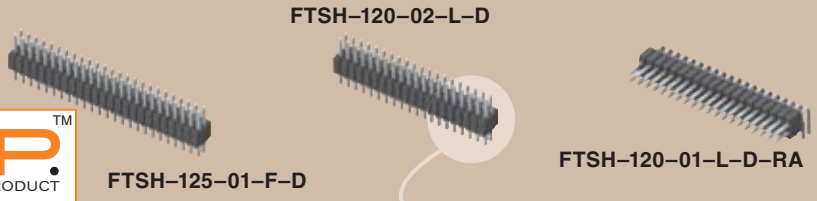




(1,27mm) .050"

FTSH SERIES



THROUGH-HOLE MICRO HEADER

SPECIFICATIONS

For complete specifications see www.samtec.com?FTSH

Insulator Material:

Black Liquid Crystal Polymer

Terminal Material:

Phosphor Bronze

Plating:

Sn or Au over 50µ" (1,27µm) Ni

Current Rating:

1.75A @ 80°C ambient

Operating Temp Range:

-55°C to +125°C

RoHS Compliant:

Yes

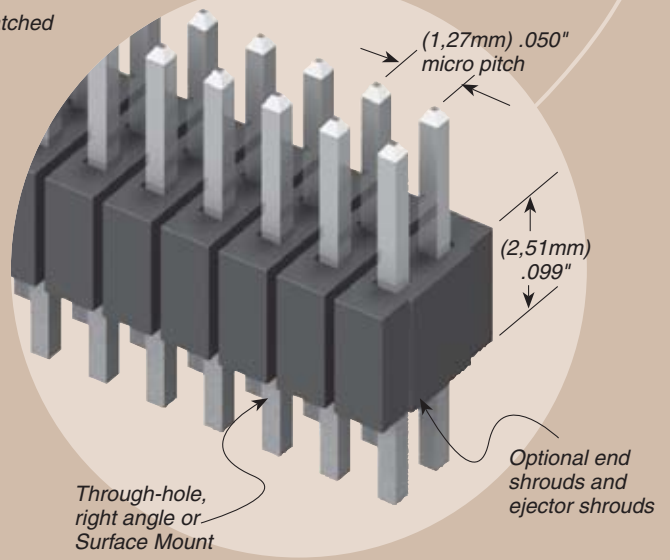


Mates with:
FFSD, CLP, FLE, SFMC

Impedance matched for high speed applications (Mated with CLP series)

APPLICATION SPECIFIC OPTION

Molded Pick & Place pads available. Call Samtec.



Mates with socket strips or IDC cable

FTSH	1	NO. PINS PER ROW	LEAD STYLE	PLATING OPTION	D	TAIL OPTION	OTHER OPTIONS
		02 thru 50	Specify LEAD STYLE from chart	-F = Gold flash on post, Matte Tin on tail -L = 10µ" (0,25µm) Gold on post, Matte Tin on tail		Leave blank for straight tail -RA = Right Angle	-ES = End Shroud (Style -02 & -03) 9 pins/row min. -EP = End Shroud with Guide Post (Style -02 & -03) 9 pins/row min. -EL = End Shroud with Board Lock (Style -02 & -03) 9 pins/row min. -EJ = Ejector Shroud (Style -01 only) 10 pins/row min. 25 pins/row max. -RA not available -K = Keying Shroud (For mating with FFSD Style -01 only, 05-25 pins/row only, 13, 17, 20 & 25 only with shrouds)

No. of positions x (1,27) .050 + Z

(1,27) .050

No. of positions x (1,27) .050

(1,27) .050

LEAD STYLE	A	OPTION	Z
-01	(3,05) .120	-ES	(1,55) .061
-02	(1,91) .075	-EJ	(15,77) .621
-03	(1,65) .065	-EP	(5,87) .231
-04	(3,81) .150	-EL	(6,53) .257

Note: Other Gold plating options available. Contact Samtec.

Note: See SFM/TFM for positive alignment feature.

Note: Some sizes, styles and options are non-standard, non-returnable.

Processing:
Lead-Free Solderable:
Yes



www.samtec.com

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM